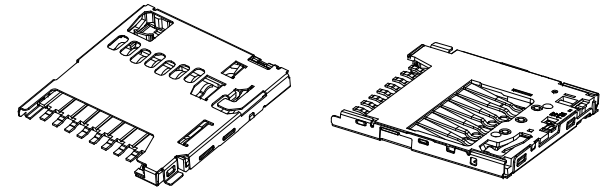
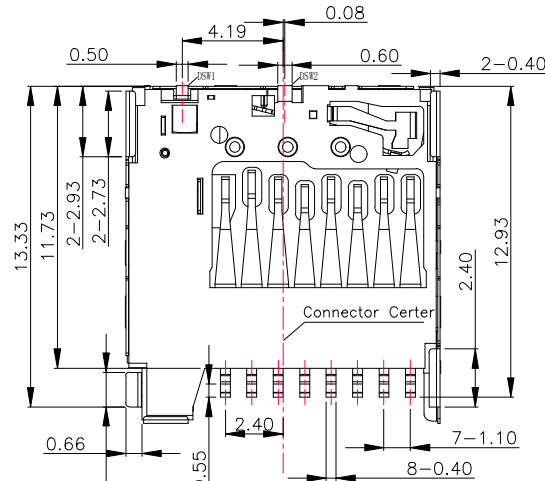
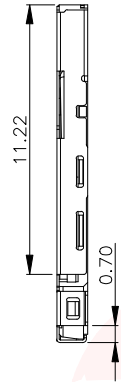
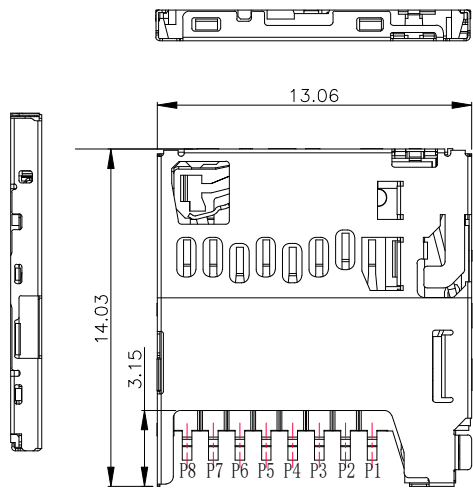


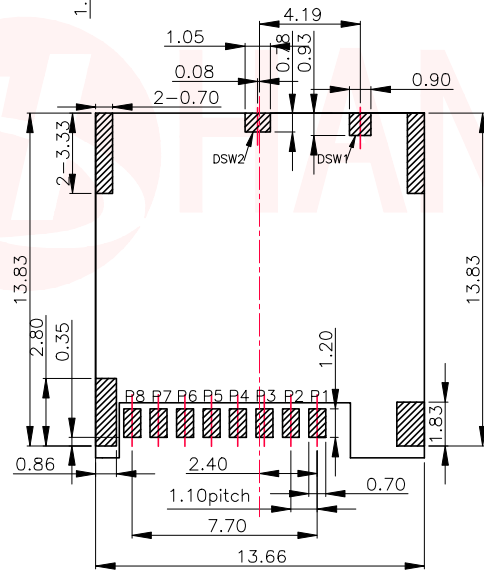
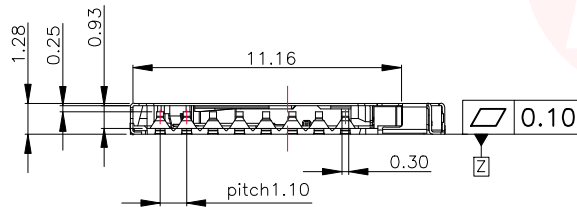


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



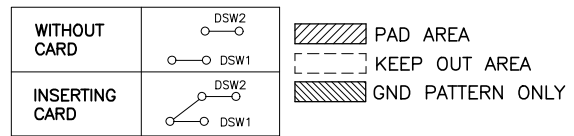
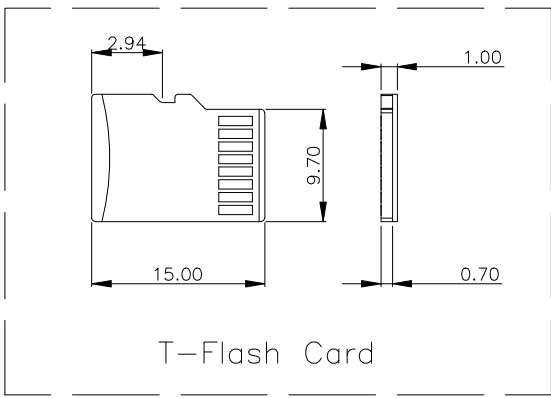
Specification

- 1.MATERIAL:**
 1.1 Insulator:High Temperature Thermoplastic, LCP SZ6505 black 94V-0.
 1.2 Contact: Beryllium copper(7035-TM06, T=0.15mm)
 1.3 Shell: SUS301-3/4H T=0.10mm
- 2.Plating:**
 2.1 Contact: Plated 80u"min Ni Overall
 Plated 1u"min Au Selective contact area
 Selective 1u"min AU over Ni on solder area
 2.2 Shell: Solder tail Plated 1u"min AU overl 50u"min Ni
- 3.Property:**
 3.1 Current Rating :0.5A AC/DC max.
 3.2 Voltage Rating :12V AC/DC
 3.3 Ambient Temperature Range :-20°C~+60°C
 3.4 Ambient Humidity Range :95% R.H. Max.
 3.5 Contact Resistance:100mΩ max.
 3.6 Insulation Resistance:1000MΩ min./500VDC
 3.7 Durability:5,000 cycles



PIN NO.	NAME	YYPE	DESCRIPTION
P1	DAT2	I/O/PP	DATE LINE(BIT2)
P2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
P3	CMD	PP	COMMAND RESPONSE
P4	VDD	S	SUPPLY VOLTAGE
P5	CLK	I	CLOCK
P6	VSS	S	SUPPLY VOLTAGE GROUND
P7	DAT0	I/O/PP	DATE LINE(BIT0)
P8	DAT1	I/O/PP	DATE LINE(DIT1)

RECOMMENDED P.C.B HOLE LAYOUT
 COMPONENT SIDE VIEW(TOLERANCE: +/-0.05)



UNLESS OTHERWISE SPECIFED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	MICRO SD PUSH PUSH 1.28H		
X :±0.5	X :±2°	DWN	xiong	TF-022	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
		REV: A4			
CUSTOMER COPY					